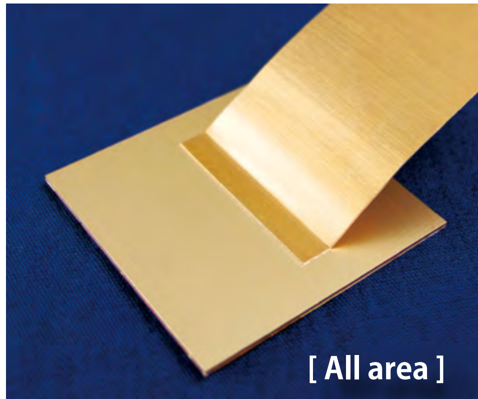
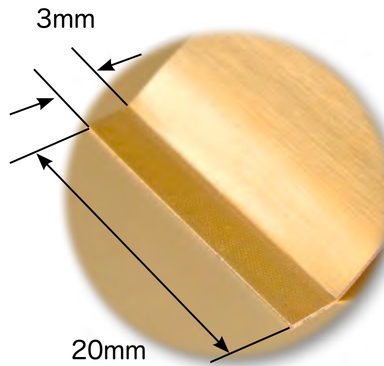
SoundBonding application

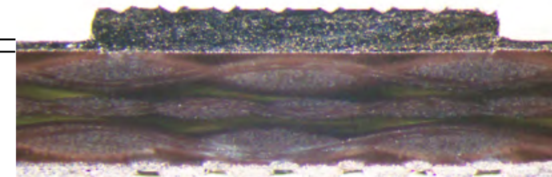
〈FR4 基板上 への FFC の接合〉

全面／ 5 箇所 一括同時音波接合

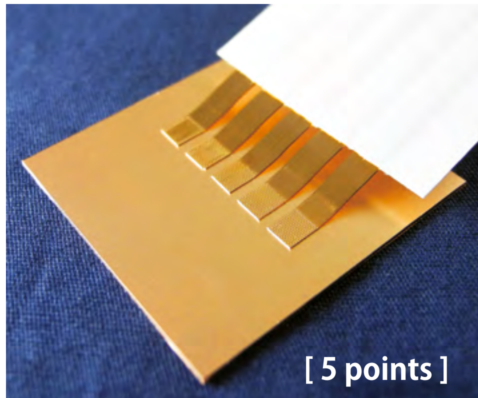


FR4 substrate : t =0.3mm, Cu layer : t =35 μm
Cu foil : t =0.1mm

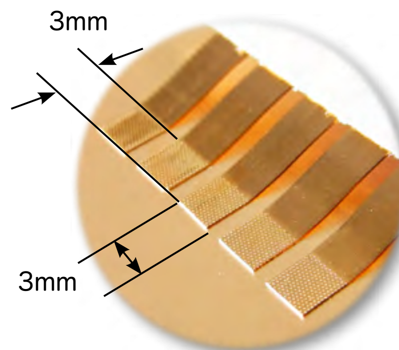


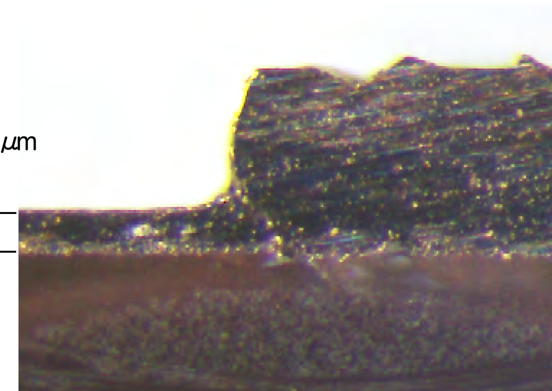


[The cross section]



FR4 substrate : t =0.3mm, Cu layer : t =35 μm
Cu foil : t =0.15mm





[The expanded cross section]

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